

### PROTECTION PRODUCTS

#### Description

The SMDAxxCN-5 series of transient voltage suppressors are designed to protect components which are connected to data and transmission lines from voltage surges caused by ESD (electrostatic discharge), EFT (electrical fast transients), and lightning.

TVS diodes are characterized by their high surge capability, low operating and clamping voltages, and fast response time. This makes them ideal for use as board level protection of sensitive semiconductor components. The SMDAxxCN-5 is designed to provide transient suppression on multiple data lines and I/O ports. The low profile SO-8 design allows the user to protect up to five data and I/O lines with one package.

The SMDAxxCN-5 TVS diode array will meet the surge requirements of IEC 61000-4-2 (Formerly IEC 801-2), Level 4, "Human Body Model" for air and contact discharge.

#### Features

- ◆ 300 watts peak pulse power ( $t_p = 8/20\mu s$ )
- ◆ Transient protection for data lines to  
**IEC 61000-4-2 (ESD) 15kV (air), 8kV (contact)**  
**IEC 61000-4-4 (EFT) 40A (5/50ns)**  
**IEC 61000-4-5 (Lightning) 12A (8/20 $\mu s$ )**
- ◆ Protects up to 5 bidirectional lines
- ◆ Low operating voltage
- ◆ Low clamping voltage
- ◆ Solid-state silicon avalanche technology

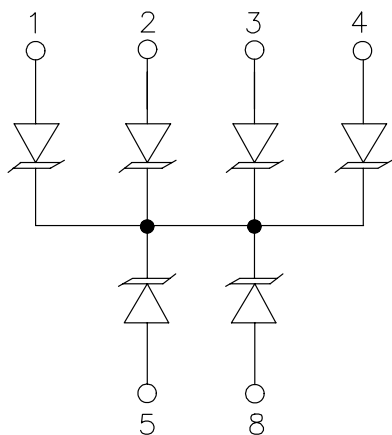
#### Mechanical Characteristics

- ◆ JEDEC SO-8 package
- ◆ Molding compound flammability rating: UL 94V-0
- ◆ Marking : Part number, date code, logo
- ◆ Packaging : Tube or Tape and Reel per EIA 481

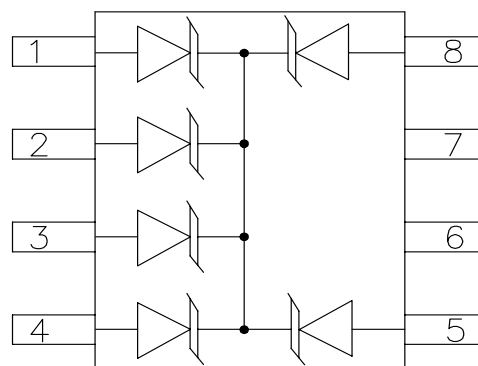
#### Applications

- ◆ RS-232 Data Lines
- ◆ RS-423 Data Lines
- ◆ LAN/WAN Equipment
- ◆ Servers
- ◆ Notebook & Desktop PC
- ◆ Set Top Box
- ◆ Peripherals

#### Circuit Diagram



#### Schematic & PIN Configuration



**SO-8 (Top View)**

**PROTECTION PRODUCTS**
**Absolute Maximum Rating**

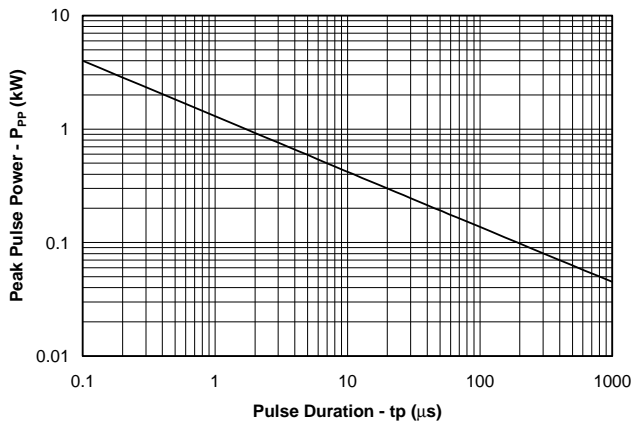
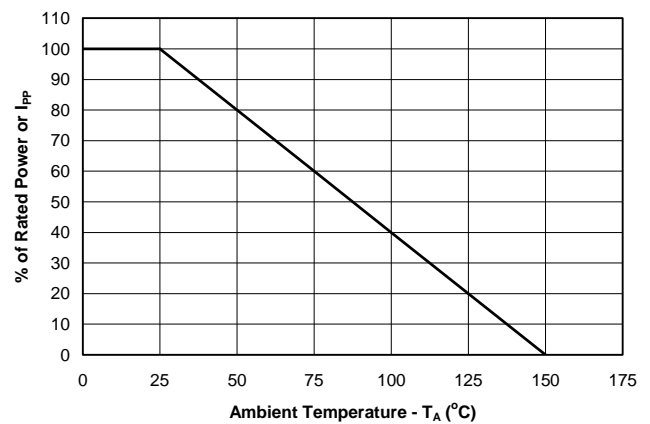
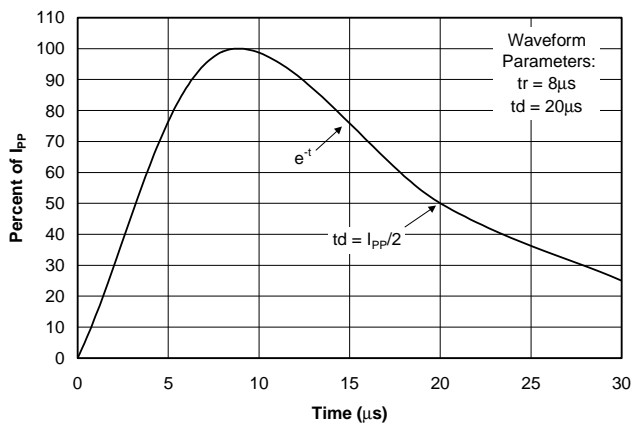
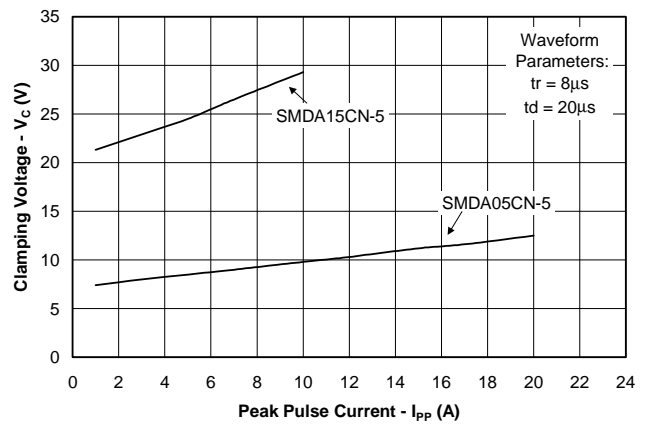
| Rating                                   | Symbol    | Value         | Units |
|--|-----------|---------------|-------|
| Peak Pulse Power ( $t_p = 8/20\mu s$ )   | $P_{pk}$  | 300           | Watts |
| Peak Pulse Current ( $t_p = 8/20\mu s$ ) | $I_{pp}$  | 20            | A     |
| Lead Soldering Temperature               | $T_L$     | 260 (10 sec.) | °C    |
| Operating Temperature                    | $T_J$     | -55 to +125   | °C    |
| Storage Temperature                      | $T_{STG}$ | -55 to +150   | °C    |

**Electrical Characteristics**
**SMDA05CN-5**

| Parameter                  | Symbol    | Conditions                                       | Minimum | Typical | Maximum | Units   |
|----------------------------|-----------|--|---------|---------|---------|---------|
| Reverse Stand-Off Voltage  | $V_{RWM}$ |  |         |         | 5       | V       |
| Reverse Breakdown Voltage  | $V_{BR}$  | $I_t = 1mA$                                      | 6       |         |         | V       |
| Reverse Leakage Current    | $I_R$     | $V_{RWM} = 5V, T=25^\circ C$                     |         |         | 10      | $\mu A$ |
| Clamping Voltage           | $V_C$     | $I_{pp} = 1A, t_p = 8/20\mu s$                   |         |         | 9.8     | V       |
| Clamping Voltage           | $V_C$     | $I_{pp} = 10A, t_p = 8/20\mu s$                  |         |         | 11      | V       |
| Maximum Peak Pulse Current | $I_{pp}$  | $t_p = 8/20\mu s$                                |         |         | 20      | A       |
| Junction Capacitance       | $C_J$     | Between I/O Pins and Gnd<br>$V_R = 0V, f = 1MHz$ |         |         | 350     | pF      |

**SMDA15CN-5**

| Parameter                  | Symbol    | Conditions                                       | Minimum | Typical | Maximum | Units   |
|----------------------------|-----------|--|---------|---------|---------|---------|
| Reverse Stand-Off Voltage  | $V_{RWM}$ |  |         |         | 15      | V       |
| Reverse Breakdown Voltage  | $V_{BR}$  | $I_t = 1mA$                                      | 16.7    |         |         | V       |
| Reverse Leakage Current    | $I_R$     | $V_{RWM} = 15V, T=25^\circ C$                    |         |         | 1       | $\mu A$ |
| Clamping Voltage           | $V_C$     | $I_{pp} = 1A, t_p = 8/20\mu s$                   |         |         | 24      | V       |
| Clamping Voltage           | $V_C$     | $I_{pp} = 10A, t_p = 8/20\mu s$                  |         |         | 30      | V       |
| Maximum Peak Pulse Current | $I_{pp}$  | $t_p = 8/20\mu s$                                |         |         | 10      | A       |
| Junction Capacitance       | $C_J$     | Between I/O Pins and Gnd<br>$V_R = 0V, f = 1MHz$ |         |         | 75      | pF      |

**PROTECTION PRODUCTS**
**Typical Characteristics**
**Non-Repetitive Peak Pulse Power vs. Pulse Time**

**Power Derating Curve**

**Pulse Waveform**

**Clamping Voltage vs. Peak Pulse Current**


## PROTECTION PRODUCTS

### Applications Information

#### Device Connection Options for Protection of Four or Five Data Lines

The SMDAxxCN-5 can be configured to protect either four or five bidirectional data lines. The options for connecting the devices are as follows:

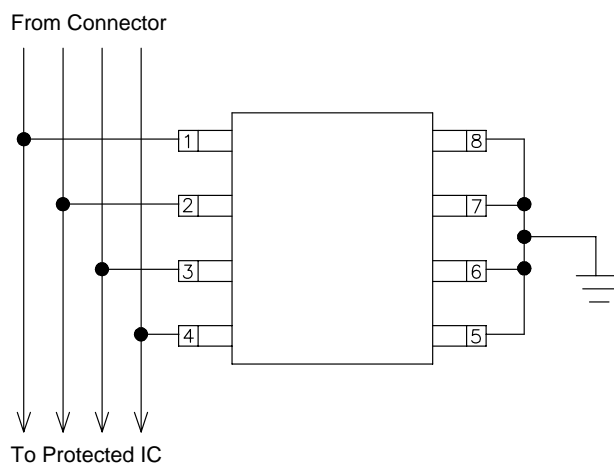
1. Bidirectional protection of four I/O lines is achieved by connecting pins 1, 2, 3, and 4 to the data lines. Pins 5, 6, 7, and 8 are connected to ground. The ground connection should be made directly to the ground plane for best results. The path length is kept as short as possible to reduce the effects of parasitic inductance in the board traces. In this configuration, the device can withstand the maximum specified transient impulse on four lines simultaneously.
2. Bidirectional protection of five I/O lines is achieved by connecting pins 1, 2, 3, 4, and 5 to the data lines. Pins 6, 7, and 8 are connected to ground. The ground connection should be made directly to the circuit board ground plane for best results. In this configuration, the device can withstand the maximum rated transient impulse on any two lines simultaneously.

#### Circuit Board Layout Recommendations for Suppression of ESD.

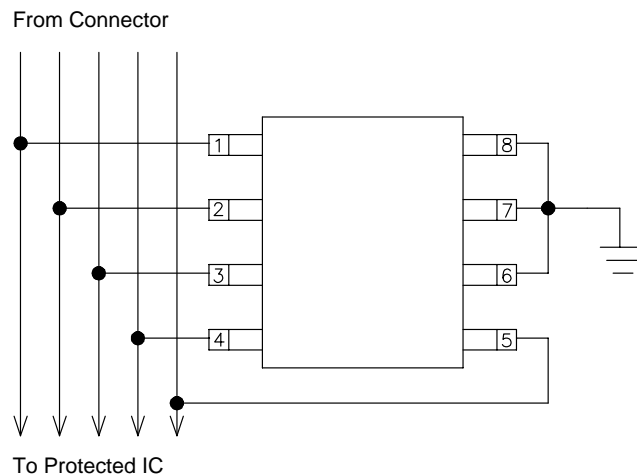
Good circuit board layout is critical for the suppression of ESD induced transients. The following guidelines are recommended:

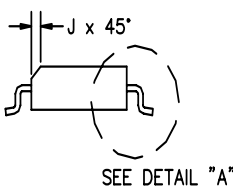
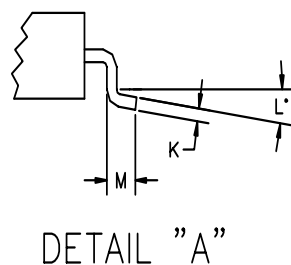
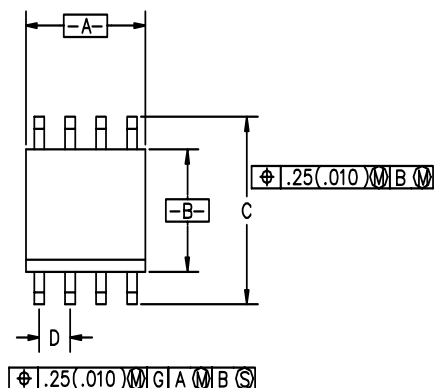
- Place the TVS near the input terminals or connectors to restrict transient coupling.
- Minimize the path length between the TVS and the protected line.
- Minimize all conductive loops including power and ground loops.
- The ESD transient return path to ground should be kept as short as possible.
- Never run critical signals near board edges.
- Use ground planes whenever possible.

#### Protection for Four Bidirectional Lines

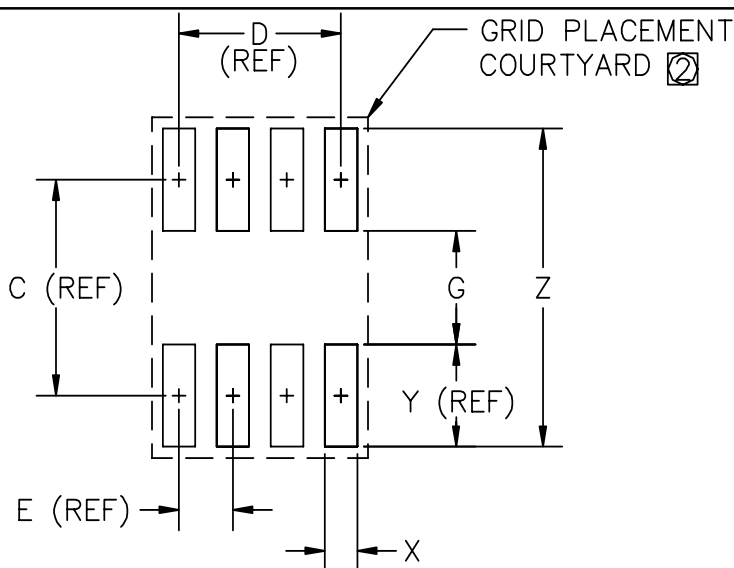


#### Protection for Five Bidirectional Lines



**PROTECTION PRODUCTS**
**Outline Drawing - SO-8**


| DIM <sup>N</sup> | INCHES |      | MM   |      | NOTE |
|------------------|--------|------|------|------|------|
|                  | MIN    | MAX  | MIN  | MAX  |      |
| A                | .188   | .197 | 4.80 | 5.00 |      |
| B                | .149   | .158 | 3.80 | 4.00 |      |
| C                | .228   | .244 | 5.80 | 6.20 |      |
| D                | .050   | BSC  | 1.27 | BSC  |      |
| E                | .013   | .020 | 0.33 | 0.51 |      |
| F                | .004   | .010 | 0.10 | 0.25 |      |
| H                | .053   | .069 | 1.35 | 1.75 |      |
| J                | .011   | .019 | 0.28 | 0.48 |      |
| K                | .007   | .010 | .19  | .25  |      |
| L                | 0°     | 8°   | 0°   | 8°   |      |
| M                | .016   | .050 | 0.40 | 1.27 |      |

**Land Pattern - SO-8**


| DIM <sup>N</sup> | INCHES |     | MM   |      | NOTE |
|------------------|--------|-----|------|------|------|
|                  | MIN    | MAX | MIN  | MAX  |      |
| C                | —      | .19 | —    | 5.00 | —    |
| D                | —      | .15 | —    | 3.81 | —    |
| E                | —      | .05 | —    | 1.27 | —    |
| G                | .10    | .11 | 2.60 | 2.80 | —    |
| X                | .02    | .03 | .60  | .80  | —    |
| Y                | —      | .09 | —    | 2.40 | —    |
| Z                | —      | .29 | 7.20 | 7.40 | —    |

② GRID PLACEMENT COURTYARD IS 12x16 ELEMENTS (6 mm X 8mm) IN ACCORDANCE WITH THE INTERNATIONAL GRID DETAILED IN IEC PUBLICATION 97.

① CONTROLLING DIMENSION: MILLIMETERS

**PROTECTION PRODUCTS****Ordering Information**

| <b>Part Number</b> | <b>Working Voltage</b> | <b>Qty per Reel</b> | <b>Reel Size</b> |
|--------------------|------------------------|---------------------|------------------|
| SMDA05CN-5.TB      | 5V                     | 500                 | 7 Inch           |
| SMDA05CN-5.TE      | 5V                     | 2,500               | 13 Inch          |
| SMDA15CN-5.TB      | 15V                    | 500                 | 7 Inch           |
| SMDA15CN-5.TE      | 15V                    | 2,500               | 13 Inch          |

**Note:**

(1) No suffix indicates tube pack.

**Contact Information**

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